



Press Release

Unisem Introduces New High Density Leadframe Based Packaging Using Technology developed by TL Li (Patent Pending)

Kuala Lumpur, Malaysia – June 7, 2010 – Unisem today announced the introduction of a new high density leadframe packaging technology, the Leadframe Grid Array (LFGA). This latest offering, developed by TL Li, the founder and major shareholder of QPL International Holdings Limited (“QPL”), and pending for patent, is a solution that offers I/O densities traditionally only found in ball grid array packages, yet it uses a much more cost effective material set.

As consumer electronics continue to become more and more complex, semiconductor manufacturers also continue to push the demand for a reduced cost packaging solution. The LFGA package provides the best of both worlds with a high density, fully populated array of I/O's attached to a leadframe based on their patented leadframe design and etched leadframe process. In fact the routing density of the LFGA makes it a great replacement for a 2 layer FBGA package.

Other key benefits of the LFGA package are its shorter bond wire lengths compared to standard QFN packaging which not only helps improve the electrical performance, but also helps to reduce material costs. Package footprint reduction is also benefit with the LFGA package's ability to take a 10x10, 72 lead QFN package down to 5.5 squared body size. Finally, the LFGA offers a higher MSL level due to the absence of organic materials in the interface of mold compound and leadframe.

“I believe this is another sensational invention after the QFN package that currently dominates the packaging world. This package offers a better footprint with higher IO density, and better thermal and electrical performance. It is also thinner with higher IO and most importantly, offers a much better yield at front end assembly”, stated TL Li, the founder and major shareholder of QPL, who is also its chairman and one of its executive directors.

“We are very excited about the LFGA packaging technology our development teams have created with this technology developed by TL Li”, stated C.H. Ang, Group COO of the Unisem Group. “We have seen a definitive market need for a higher I/O, lower cost packaging solution and the LFGA package meets this requirement perfectly”, continued Ang.

The LFGA package is available now in small quantities for customer evaluation.

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 9,000 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about Unisem, please visit www.unisemgroup.com.

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